

Single N-channel MOSFET

KFK4B02910L Datasheet

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1. GENERAL DESCRIPTION

Gate resistor installed Single N-channel MOSFET for lithium-ion secondary battery protection circuits.

2. FEATURES

- Drain-source On-state Resistance: $R_{DS(on)}$ typ = 22 m Ω (V_{GS} = 3.8 V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

3. MARKING SYMBOL: T9

4. PACKAGING

Embossed type (Thermo-compression sealing): 20,000 pcs / reel (standard)

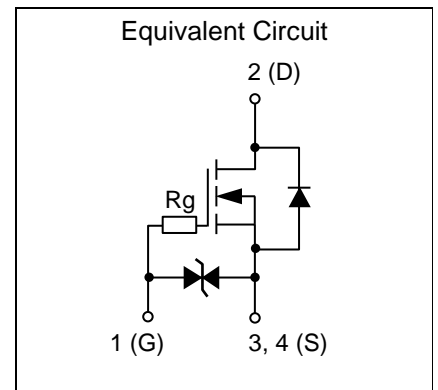
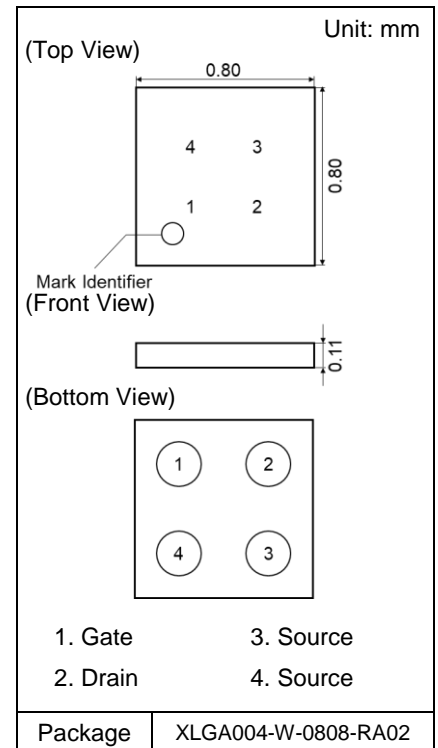
5. ABSOLUTE MAXIMUM RATINGS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source Voltage	VDS	22	V
Gate-source Voltage	VGS	± 12	V
Drain Current	DC ^{*1}	ID1	3.7
	DC ^{*2}	ID2	5.8
	DC ^{*3}	ID3	7.6
	Pulsed ^{*4}	IDp	37.0
Total Power Dissipation	DC ^{*1}	PD1	0.41
	DC ^{*2}	PD2	1.00
	DC ^{*3}	PD3	1.71
Operating Junction and Storage Temperature Range	Tj, Tstg	- 55 to + 150	$^\circ\text{C}$

6. THERMAL CHARACTERISTICS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth1 ^{*1}	300	$^\circ\text{C} / \text{W}$
	Rth2 ^{*2}	125	
	Rth3 ^{*3}	73	

- Note
- *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board partially covered with copper pad (65.7 mm² area, 36 μm thickness).
 - *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board fully covered with copper pad (619 mm² area, 36 μm thickness).
 - *3 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).
 - *4 t = 10 μs , Duty Cycle $\leq 1\%$.



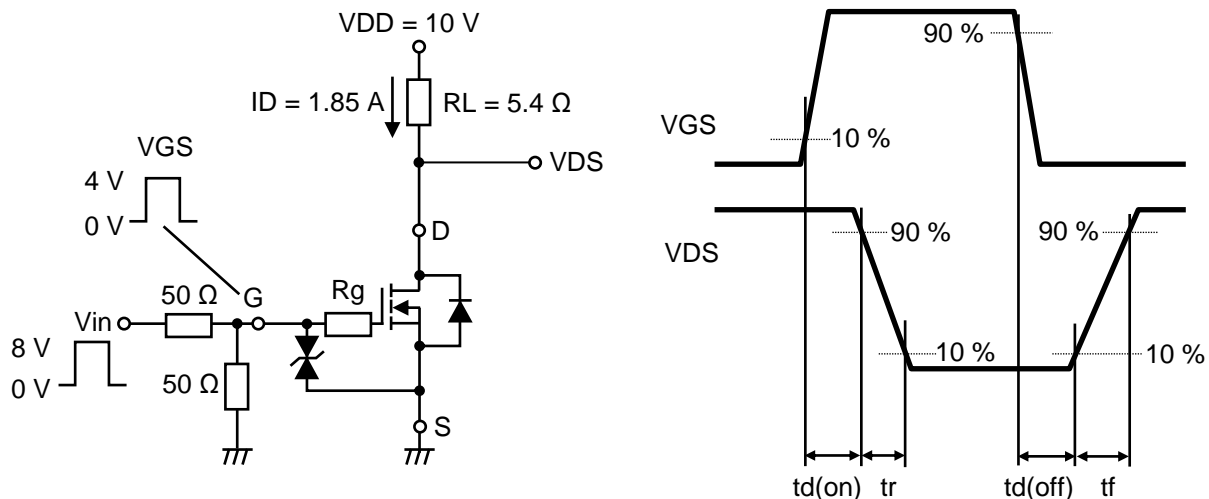
7. ELECTRICAL CHARACTERISTICS $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = 1 mA, VGS = 0 V	22			V
Zero Gate Voltage Drain Current	IDSS	VDS = 22 V, VGS = 0 V			1	μA
Gate-source Leakage Current	IGSS	VGS = ± 8 V, VDS = 0 V			± 10	μA
Gate-source Threshold Voltage	Vth	ID = 84 μA , VDS = 10 V	0.35	0.9	1.4	V
Drain-source On-state Resistance	RDS(on)1	ID = 1.85 A, VGS = 4.5 V	16	21	27	m Ω
	RDS(on)2	ID = 1.85 A, VGS = 3.8 V	17	22	28	
	RDS(on)3	ID = 1.85 A, VGS = 3.1 V	17	25	32	
	RDS(on)4	ID = 1.85 A, VGS = 2.5 V	18	31	61	
Body Diode Forward Voltage	VF(s-d)	IF = 1.85 A, VGS = 0 V		0.75	1.00	V
Input Capacitance *1	Ciss	VDS = 10 V, VGS = 0 V f = 1 kHz		540		pF
Output Capacitance *1	Coss			80		
Reverse Transfer Capacitance *1	Crss			70		
Turn-on Delay Time *1, *2	td(on)	VDD = 10 V, VGS = 0 to 4 V		170		ns
Rise Time *1, *2	tr	ID = 1.85 A		290		
Turn-off Delay Time *1, *2	td(off)	VDD = 10 V, VGS = 4 to 0 V		730		
Fall Time *1, *2	tf	ID = 1.85 A		530		
Total Gate Charge *1	Qg	VDD = 10 V, VGS = 4 V ID = 3.7 A		5.0		nC
Gate-source Charge *1	Qgs			1.2		
Gate-drain Charge *1	Qgd			1.6		
Gate Resistance *1	Rg	f = 1 MHz	400	700	1000	Ω

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Guaranteed by design, not subject to production testing.

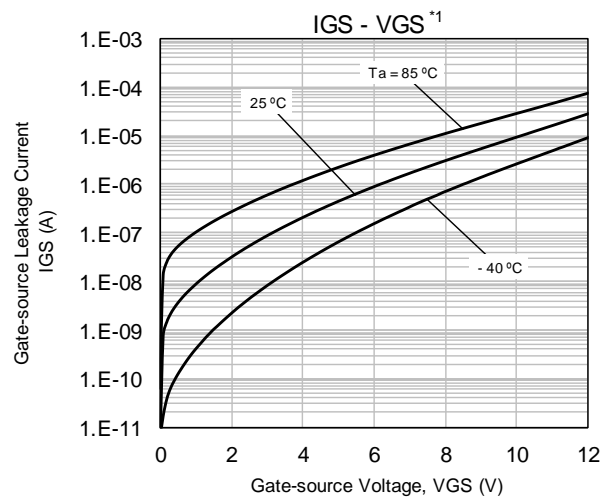
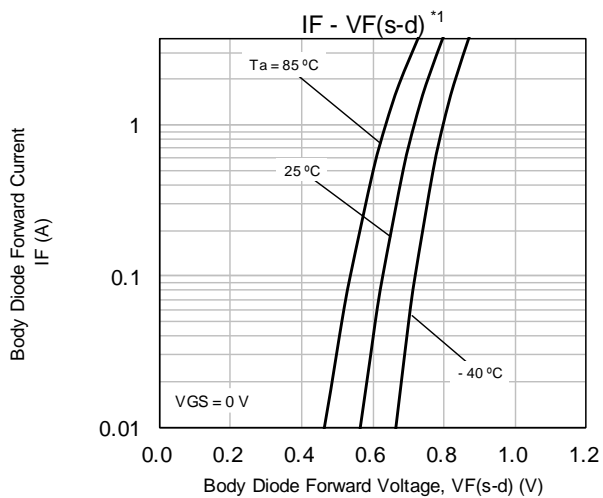
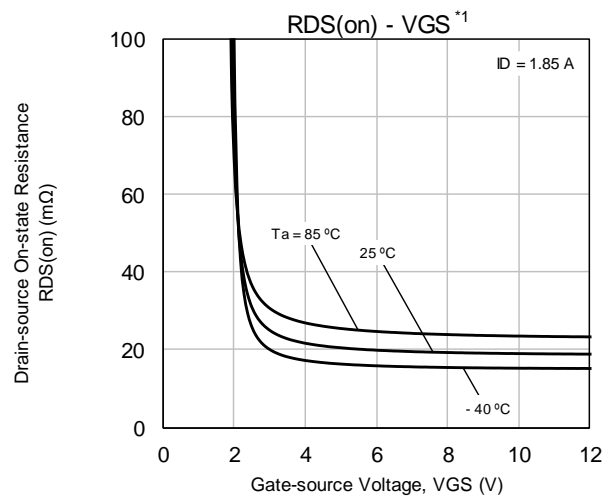
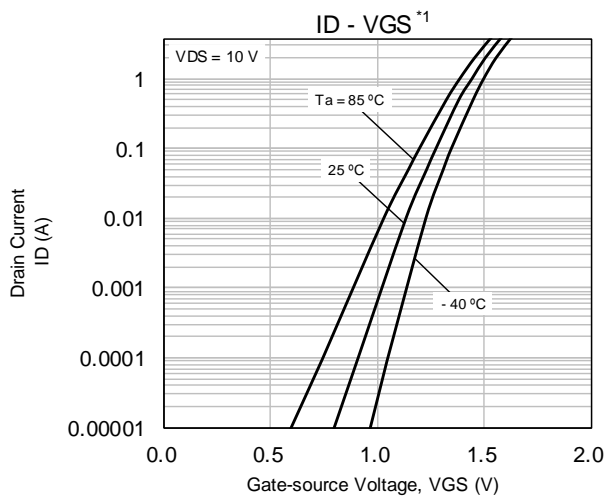
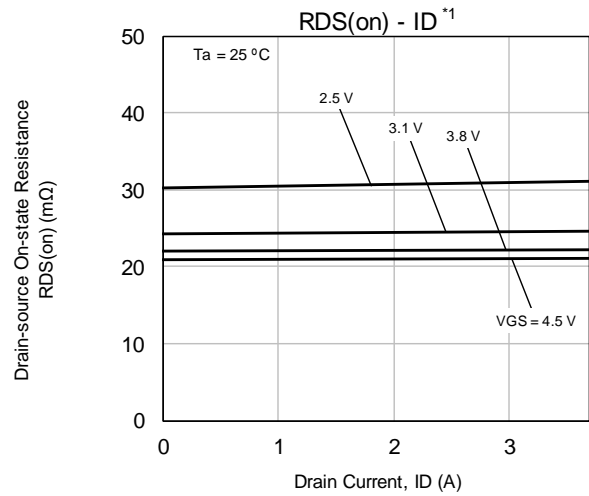
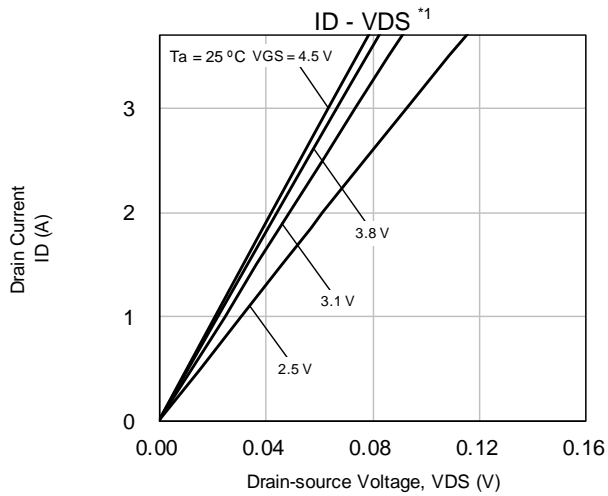
*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.



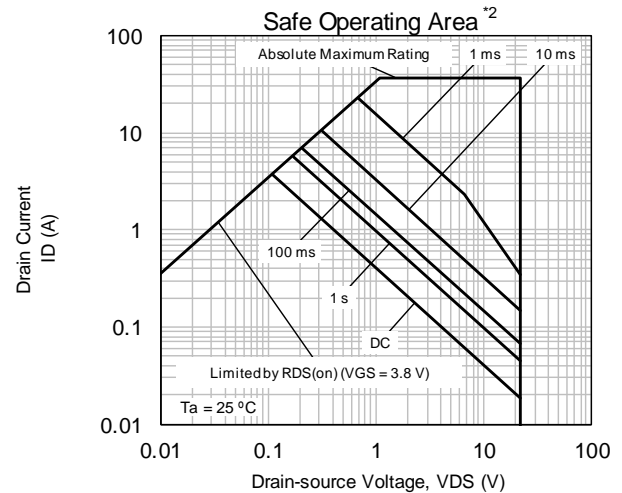
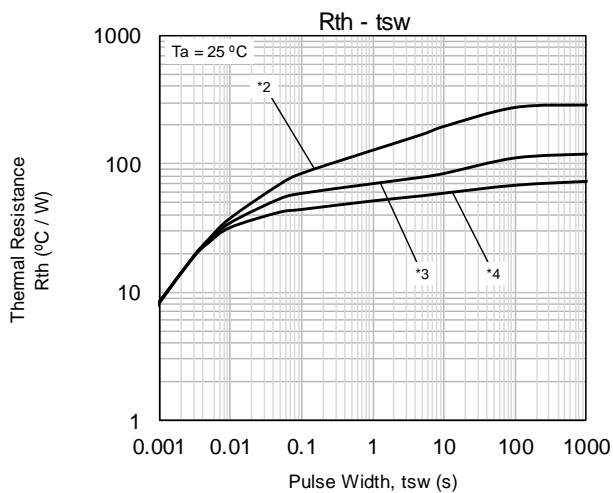
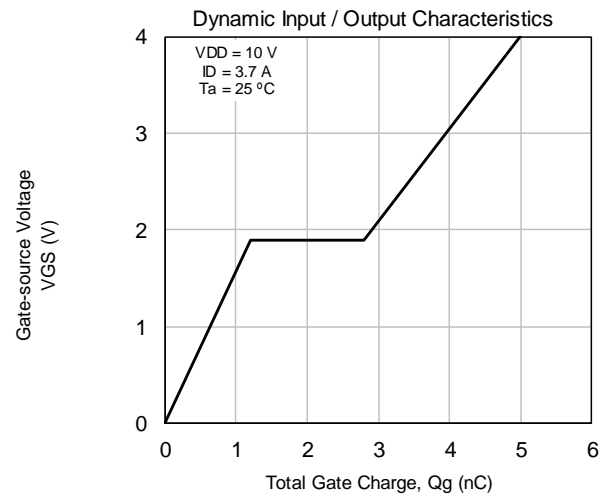
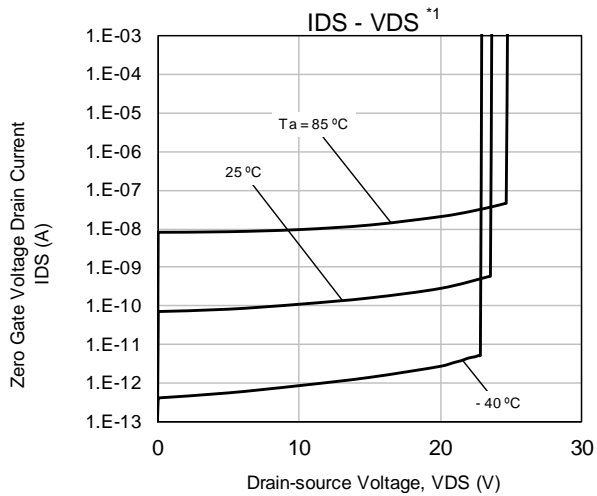
8. ELECTROSTATIC DISCHARGE CHARACTERISTIC $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Standard	Test Type	Symbol	Conditions	Class	Value	Unit
AEC-Q101-001	Human Body Model	HBM	C = 100 pF, R = 1.5 k Ω	H2	> 2 to ≤ 4	kV

9. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)



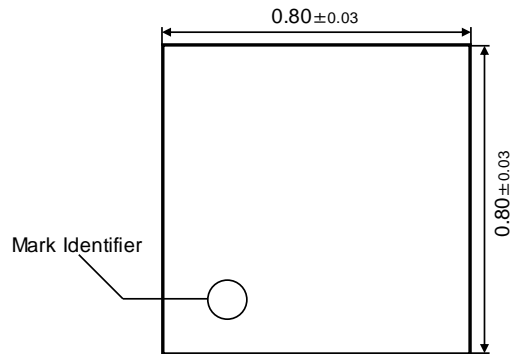
Note

- ^{*1} Pulse measurement.
- ^{*2} Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board partially covered with copper pad (65.7 mm² area, 36 μm thickness).
- ^{*3} Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board fully covered with copper pad (619 mm² area, 36 μm thickness).
- ^{*4} Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

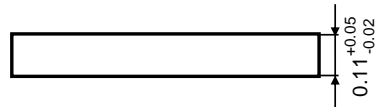
10. OUTLINE

(Top View)

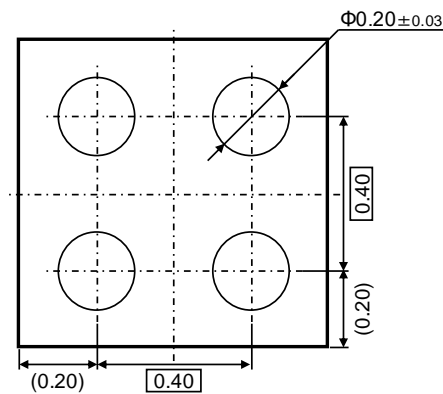
Unit: mm



(Front View)

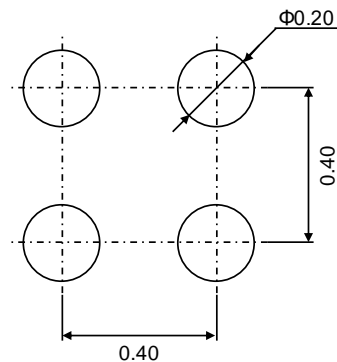


(Bottom View)



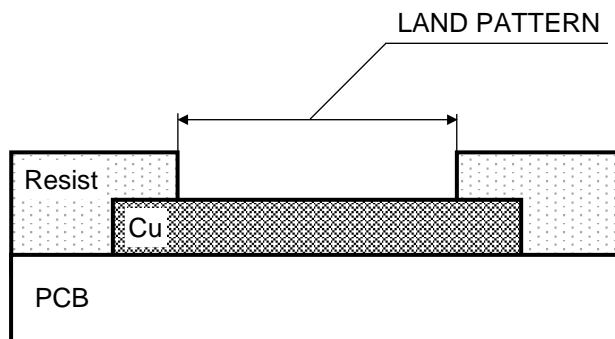
11. LAND *1 & STENCIL PATTERN (Reference)

Unit: mm



Note *1 The definition of land pattern is referred to next page.

DEFINITION OF LAND PATTERN



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design.

Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.

12. REVISION HISTORY

Date	Revision	Description
2022.8.22	1.00	1. Initially issued.

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